

conga-XAF

High graphics performance with low power consumption

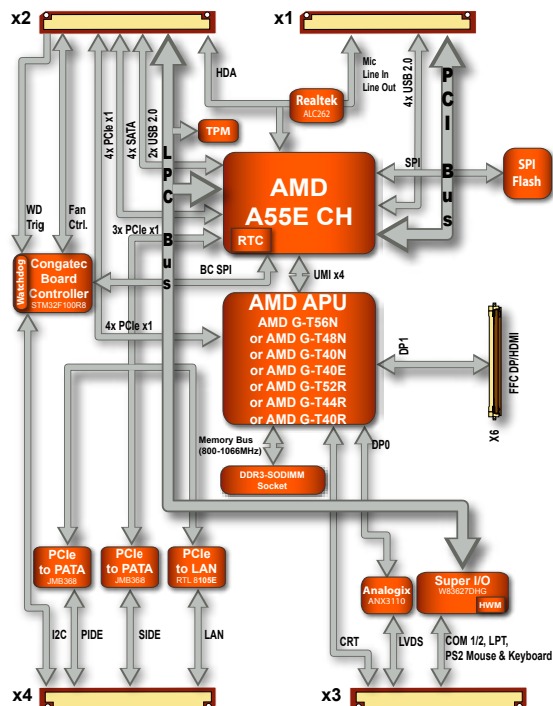


- Based on AMD Embedded G-Series Processors
- Best price/performance ratio
- High performance graphics



Formfactor	ETX® Spec 2.7. without ISA Support XTX™ Extensions
CPU	AMD Embedded G-Series Processors AMD G-T56N 1.6 GHz Dual Core L1 cache 64KB L2 cache 512kB x2 TDP 18 W AMD G-T52R 1.5 GHz Single Core L1 cache 64KB L2 cache 512kB TDP 18 W AMD G-T40R 1.0 GHz Single Core L1 cache 64KB L2 cache 512kB TDP 5.5 W AMD G-T40E 1.0 GHz Dual Core L1 cache 64KB L2 cache 512kB x2 TDP 6.5 W
DRAM	Single channel up to one 4 GB DDR3 SO-DIMM memory (up to 1066 MHz)
Chipset	AMD A55E Controller Hub
Ethernet	10/100M Fast Ethernet Realtek RTL8105E
I/O Interfaces	4x PCI Express™ x1 lanes 4x Serial ATA® 2x EIDE (up to UDMA-66/100) 6x USB 2.0 PCI Bus (Rev. 2.3 compliant / 33 MHz) 2x Express Card LPC Bus I²C (Fast Mode / 400 kHz Multi Maser) Floppy LPT 2x COM PS/2
Sound	High Definition Audio Interface and Analog MIC Line In Line Out by on-module HDA codec
Graphics	Integrated High Performance Video DirectX®11 graphics with UVD 3.0 Integrated VGA DAC Dual Simultaneous Display Support no PEG support
LVDS	2x24 Bit 800x600 to 1920x1200@60Hz; VESA standard or JEDIA data mapping; Automatic Panel Detection via EDID/EPI
DisplayPort	1x DisplayPort 1.1a shared with HDMI port resolutions up to 2560x1600 - 18W APU 1920x1200 - 9W APU
HDMI or DVI	1x HDMI 1.3 Port shared with DisplayPort resolutions up to 1920x1080 / 1920x1200 for DVI mode
CRT	400 MHz RAMDAC resolutions up to 2560x1600 - 18W APU 1920x1200 9W APU
congatec Board Controller	Multi Stage Watchdog non-volatile User Data Storage Manufacturing and Board Information Board Statistics BIOS Setup Data Backup I²C bus (fast mode / 400 kHz / multi-master) Power Loss Control
Embedded BIOS Features	AMI-Aptio UEFI BIOS with congatec Embedded BIOS features
Security	The conga-XAF can be optionally equipped with a discrete "Trusted Platform Module" (TPM). It is capable of calculating efficient hash and RSA algorithms with key lengths up to 2,048 bits and includes a real random number generator. Security sensitive applications such as gaming and e-commerce will benefit also with improved authentication integrity and confidence levels.
Power Management	ACPI 3.0 with battery support
Operating Systems	Microsoft® Windows8 Microsoft® Windows7 Microsoft® Windows XP Microsoft® Windows® embedded Standard Microsoft® Windows CE 6.0 Windows Embedded Compact 7 Linux
Power Consumption	Typ. application: 9 .. 18 W. see manual for full details CMOS Battery Backup
Temperature	Operating: 0 .. +60°C Storage: -20 .. +80°C
Humidity	Operating: 10 - 90% r. H. non cond. Storage: 5 - 95% r. H. non cond.
Size	95 x 114 mm (3.7" x 4.5")

conga-XAF | Block diagram



conga-XAF | Order Information

Article	PN	Description
conga-XAF/T56N	041031	AMD G-Series dual core processor T56N 1.6GHz 1MB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T40N	041033	AMD G-Series dual core processor T40N 1.0GHz 1MB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T52R	041034	AMD G-Series single core processor T52R 1.5GHz 512kB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T44R	041035	AMD G-Series single core processor T44R 1.2GHz 512kB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T40R	041036	AMD G-Series single core processor T40R 1.0GHz 5.5W 1MB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T40E	041037	AMD G-Series dual core processor T40E 1.0GHz 6.5W 1MB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/HSP-B	041050	Standard heatspreader for XTX module conga-XAF and EAF. All standoffs are with 2.7mm bore hole
conga-XAF/HSP-T	041051	Standard heatspreader for XTX module conga-XAF and EAF. All standoffs are M2.5mm thread
conga-XAF/CSP-B	041055	Standard passive cooling solution for modules conga-XAF and EAF. All standoffs are with 2.7mm bore hole
conga-XAF/CSP-T	041056	Standard passive cooling solution for modules conga-XAF and EAF. All standoffs are M2.5mm thread
conga-XAF/CSA-B	041057	Standard active cooling solution for modules conga-XAF and EAF. Integrated 12V fan. All standoffs are with 2.7mm bore hole
conga-XAF/CSA-T	041058	Standard active cooling solution for modules conga-XAF and EAF. Integrated 12V fan. All standoffs are M2.5mm thread
DDR3-SODIMM-1066 (1GB)	068750	DDR3 SODIMM memory module with 1066MT/s and 1GB RAM
DDR3L-SODIMM-1600 (2GB)	068755	DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 2GB RAM
DDR3L-SODIMM-1600 (4GB)	068756	DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 4GB RAM
Accessories		
conga-Xeval	019482	Evaluation carrier board for XTX-modules
conga-XDVI	098637	Evaluation platform to convert SDVO to DVI-D
conga-Xdebug	041784	XTX debugging platform. Including cable for COM PS/2 and VGA
conga-FPA2	047250	Flatpanel prototype adapter to develop your own flatpanel adapter Including cables set
XTX/ETX-baseboard-socket-3	400006	Connector for ETX and XTX carrier boards height 3.0 mm packing unit 8 pieces
XTX/ETX-baseboard-socket-9.5	400009	Connector for ETX and XTX carrier boards height 9.5 mm packing unit 8 pieces
conga-LDVI/EPI	011115	LVDS to DVI adapter board for digital fl at panels with a graphics resolution up to 1280x1024 pixel

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